

BST-505-0.4MM

ESFERAS PARA REBALLING 0.4mm 86.3g





0.2mm



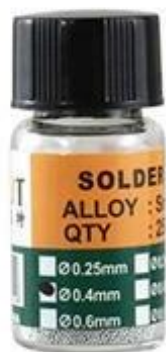
0.25mm



0.3mm



0.35mm



0.4mm



0.45mm



0.5mm



0.55mm



0.6mm



0.65mm





Brand:	BST	Name:	solder ball
Ingredients:	alloy:Sn63/Pb37	Size:	16*35mm
Specifications:	0.2mm (55.4g/10bottle), 0.25mm (68.5G/10bottle), 0.3mm (65.8G/10bottle), 0.35mm (74G/10bottle), 0.4mm (86.3G/10bottle), 0.45mm (100.8 G/10bottle), 0.5mm (119.7G/bottle10), 0.55mm (142.7G/10bottle), 0.6mm (167.7G/10bottle)		
Quantity:	25,000 / bottle		
Features:	Tin ball is mainly connected to semiconductor wafers and circuit boards and PCB boards, and small ball type tin electronic parts that transmit electronic signals.		

A bottle of 25,000





BST-505

High: 35mm

Width: 16mm

